

What is Claimed is:

1. A method of removing an optical device contained within a device package from a circuit board, wherein the device package is secured to the circuit board using
5 an adhesive pad, the method comprising:

peeling a portion of the adhesive pad away from the circuit board;

inserting an optical removal tool between the optical device and the circuit board, wherein the optical removal tool has a pair of fork portions and a cavity positioned between the fork portion, and the fork portions straddle one or more leads
10 on the optical device during the inserting step; and

prying the remainder of the adhesive pad away from the circuit board using said optical device removal tool.

2. The method of claim 1, wherein said optical device further includes electric
15 lead interconnects soldered to electric connections on the circuit board, the method further comprising breaking the soldered connections.

3. The method of claim 2, wherein the breaking the soldered connections is performed by heating the soldered connections to a temperature above a temperature
20 at which the solder of the soldered connections melt, but below a temperature that is likely to do any thermal damage to the optical device.

4. The method of claim 1, further comprising:
removing the adhesive pad from the device package.

5. An optical device remove tool, comprising:

a peeling blade, the peeling blade including a plurality of fork portions, at least one cavity extending between two ones of the plurality of fork portions; and

5 a handle extending substantially perpendicular to the peeling blade, wherein the cavity extends into the handle.

6. The optical device removal tool of claim 5, wherein the plurality of fork portions are configured to fit under an overhang separating an optical device from a
10 circuit board.

7. The optical device removal tool of claim 5, wherein electrical leads from an optical device fit within the cavity during normal operation of the optical device removal tool.